

AMENDMENTS TO THE CLAIMS:

Claims 1, 4-7, and 17 have been allowed pursuant to an Examiner's Amendment. Claims 8-16 have been cancelled. Claims 1 and 17 have been amended. This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claim 1 (Currently Amended): An electronic parts packaging structure comprising:

- a mounted body on which electronic parts are mounted;
- the electronic parts having a connection pad formed on a surface side of the electronic parts; the electronic parts being mounted on the mounted body to direct the connection pad upward,
- the connection pad being constructed of an aluminum pad and an etching stopper film covering the aluminum pad;
- the aluminum pad consisting of aluminum or an aluminum alloy;
- the etching stopper film being constructed of a laminated film having layers of film; the uppermost film of the etching stopper film being selected from a member selected from a group consisting of a copper film, a gold film, a silver film, and a conductive paste film;
- an insulating film for covering the electronic parts;
- a via hole located at least in a predetermined portion of the insulating film on the connection pad of the electronic parts; and
- a wiring pattern connected to the connection pad via the via hole,

wherein the via hole is connected to the aluminum layer pad via the etching stopper film.

Claims 2-3 (Cancelled):

Claim 4 (Previously Presented): The electronic parts packaging structure according to claim 1, wherein the mounted body is a base substrate having a wiring pattern thereon or a structural body in which an insulating film and a wiring pattern are laminated by a predetermined number on the base substrate, and the wiring pattern connected to the connection pad is connected electrically to the wiring patterns under the electronic parts via via holes formed in the insulating films.

Claim 5 (Previously Presented): The electronic parts packaging structure according to claim 4, wherein a plurality of electronic parts are packaged three-dimensionally in a state that the electronic parts are buried in a plurality of insulating films, and the plurality of electronic parts are connected mutually via the via holes formed in the insulating films and the wiring pattern.

Claim 6 (Previously Presented): The electronic parts packaging structure according to claim 1, wherein a bump of overlying electronic parts is mounted on the wiring pattern which is connected to the connection pad of the electronic parts by a flip-chip mounting.

Claim 7 (Previously Presented): The electronic parts packaging structure according to claim 1, wherein a thickness of the electronic parts is set to about 150 μm or less.

Claims 8-16 (Cancelled):

Claim 17 (Currently Amended): An electronic parts packaging structure according to claim 1, wherein the etching stopper film ~~the connection pad~~ is constructed by the laminated film selected from a group consisting of ~~aluminum film~~/nickel film/copper film, ~~aluminum film~~/nickel film/gold film, ~~aluminum film~~/nickel film/copper film/gold film, ~~aluminum film~~/nickel film/silver film, ~~aluminum film~~/chromium film/copper film, ~~aluminum film~~/conductive paste film, ~~aluminum film~~/titanium film/conductive paste film, ~~aluminum film~~/chromium film/conductive paste film, and ~~aluminum film~~/titanium film/copper film, which are formed sequentially from a bottom respectively.